

1A, 200V - 1000V Surface Mount Fast Recovery Rectifier

FEATURES

- Glass passivated junction chip
- · Ideal for automated placement
- Low forward voltage drop
- · Fast switching for high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AC (SMA)
- Molding compound meets UL 94V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: As marked
- Weight: 0.06 g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I _{F(AV)}	1	А			
V_{RRM}	200 - 1000	V			
I _{FSM}	30	Α			
T _{J MAX}	150	°C			
Package	DO-214AC (SMA)				
Configuration	Single Die				





DO-214AC (SMA)

PARAMETER	SYMBOL	RS1D-T	RS1G-T	RS1J-T	RS1K-T	RS1M-T	UNIT
Marking code on the device		RS1D	RS1G	RS1J	RS1K	RS1M	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Forward current	I _{F(AV)}	1				Α	
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode)	I _{FSM}	I _{FSM} 30			А		
Junction temperature	TJ	- 55 to +150			°C		
Storage temperature	T _{STG}	тg - 55 to +150		°C			



Taiwan Semiconductor

THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	105	°C/W		
Junction-to-case thermal resistance	R _{eJC}	32	°C/W		

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode (1)		I _F =1A, T _J =25°C	V_{F}	-	1.3	V
Reverse current @ rated V _R per diode ⁽²⁾		T _J = 25°C	I _R	-	5	μA
		T _J =125°C		-	50	μA
Junction capacitance		1 MHz, V _R =4.0V	CJ	10	-	pF
RS1D-T RS1G-T				-	150	ns
Reverse recovery time	RS1J-T	I _F =0.5A , I _R =1.0A	t _{rr}	-	250	ns
	RS1K-T RS1M-T	I _{RR} =0.25A		-	500	ns

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION						
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING		
D04 T	R3		SMA	1,800 / 7" Plastic reel		
RS1x-T (Note 1, 2)	R2	G	SMA	7,500 / 13" Paper reel		
	M2		SMA	7,500 / 13" Plastic reel		

Notes:

- 1. "x" defines voltage from 200V (RS1D-T) to 1000V (RS1M-T)
- 2. Whole series with green compound (halogen-free)

EXAMPLE P/N						
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION		
RS1M-T R3G	RS1M-T	R3	G	Green compound		

Taiwan Semiconductor

CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig1. Forward Current Derating Curve

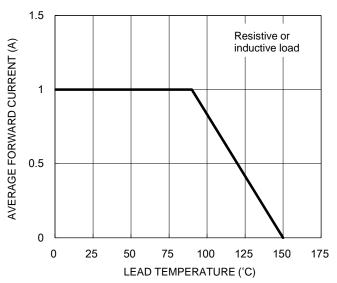


Fig2. Typical Junction Capacitance

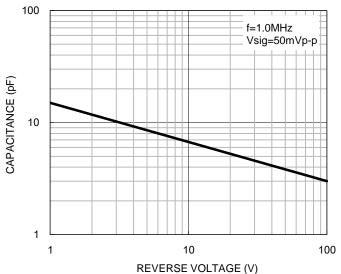


Fig3. Typical Reverse Characteristics

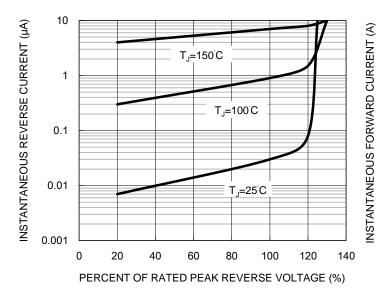
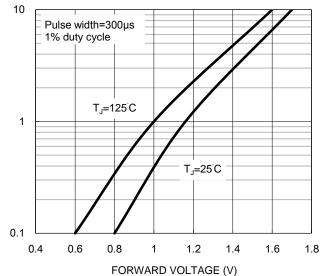


Fig4. Typical Forward Characteristics



3



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig5. Maximum Non-repetitive Forward Surge Current

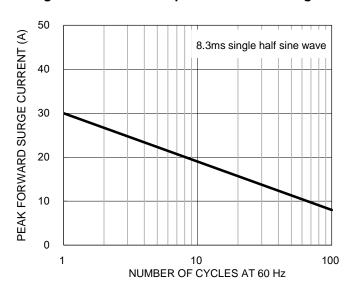
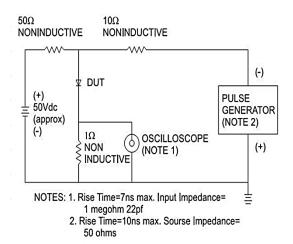
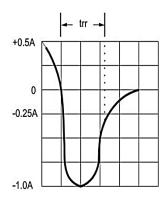


Fig6. Reverse Recovery Time Characteristic And Test Circuit Diagram

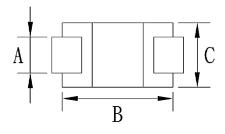


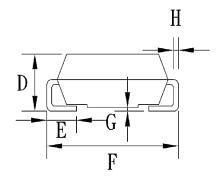




PACKAGE OUTLINE DIMENSIONS

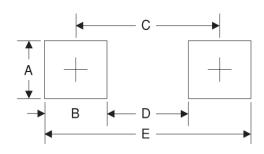
DO-214AC (SMA)





DIM	Unit (mm)		Unit ((inch)
	Min	Max	Min	Max
Α	1.27	1.58	0.050	0.062
В	4.06	4.60	0.160	0.181
С	2.29	2.83	0.090	0.111
D	1.99	2.50	0.078	0.098
Е	0.90	1.41	0.035	0.056
F	4.95	5.33	0.195	0.210
G	0.10	0.20	0.004	0.008
Н	0.15	0.31	0.006	0.012

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	1.68	0.066
В	1.52	0.060
С	3.93	0.155
D	2.41	0.095
Е	5.45	0.215

MARKING DIAGRAM



= Marking Code= Green Compound P/N G ΥW = Date Code = Factory Code



Taiwan Semiconductor

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.